

Application No. 10/707,999
Docket No. A4-1719
Amendment dated June 9, 2005
Reply to Office Action of March 9, 2005

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (currently amended): A product consisting essentially of polycrystalline chips and optionally a matrix in which the chips are dispersed, the polycrystalline chips having nanocrystalline microstructures and being formed of a material ~~at least one material~~ chosen from the group consisting of metals, metal alloys, intermetallic materials, and ceramic materials, the matrix if present being formed of a material ~~at least one material~~ chosen from the group consisting of metal, metal alloy, intermetallic materials, polymeric materials, and ceramic materials.

Claim 2 (currently amended): A product according to claim 1, wherein the ~~at least one~~ material of which the chips are formed is chosen from the group consisting of metal, metal alloy and intermetallic materials.

Claim 3 (currently amended): A product according to claim 1, wherein the ~~at least one~~ material of which the chips are formed is a ceramic material.

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Claim 4 (original): A product according to claim 1, wherein the chips have grains with a nominal size of less than 500 nm.

Claim 5 (original): A product according to claim 1, wherein the chips have grains with a nominal size of less than 100 nm.

Claim 6 (original): A product according to claim 1, wherein the product consists essentially of the chips held together by consolidation so that the product consists essentially of a nanocrystalline microstructure.

Claim 7 (previously presented): A product according to claim 1, wherein the product contains the chips dispersed in the matrix.

Claim 8 (previously presented): A product according to claim 7, wherein the chips are present in the matrix in the form of ribbons, wires or filaments.

Claim 9 (original): A product according to claim 7, wherein the chips are in the form of platelets.

Claim 10 (currently amended): A product according to claim 7,

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wherein the ~~at least one~~ material of the matrix is chosen from the group consisting of metal, metal alloy and intermetallic materials.

Claim 11 (currently amended): A product according to claim 7, wherein the ~~at least one~~ material of the matrix is a polymeric material.

Claim 12 (currently amended): A product according to claim 7, wherein the ~~at least one~~ material of the matrix is a ceramic material.

Claim 13 (currently amended): A product consisting essentially of polycrystalline chips held together by consolidation, the chips consisting entirely of grains with a nominal size of less than 500 nm so that the product consists essentially of a nanocrystalline microstructure, the chips being formed of a material ~~at least one material~~ chosen from the group consisting of metals, metal alloys, intermetallic materials, and ceramic materials.

Claim 14 (original): A product according to claim 13, wherein the chips are formed of a material chosen from the group consisting of metal, metal alloy and intermetallic materials.

Claim 15 (original): A product according to claim 13, wherein the

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chips are formed of an inorganic material chosen from the group consisting of ceramic materials.

Claim 16 (original): A product according to claim 13, wherein the grains of the chips have a nominal size of less than 300 nm.

Claim 17 (currently amended): A product comprising polycrystalline chips dispersed in a matrix, the chips being in the form of particulates, ribbons, wires, filaments and/or platelets that consist entirely of grains with a nominal size of less than 500 nm, the chips being formed of a material ~~at least one material~~ chosen from the group consisting of metals, metal alloys, intermetallic materials, and ceramic materials, the matrix being formed of a material ~~at least one material~~ chosen from the group consisting of metal, metal alloy, intermetallic materials, polymeric materials, and ceramic materials.

Claim 18 (original): A product according to claim 17, wherein the chips are formed of a material chosen from the group consisting of metal, metal alloy and intermetallic materials.

Claim 19 (original): A product according to claim 17, wherein the chips are formed of an inorganic material chosen from the group consisting of

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ceramic materials.

Claim 20 (original): A product according to claim 17, wherein the grains of the chips have a nominal size of less than 300 nm.

Claim 21 (original): A product according to claim 17, wherein the chips are in the form of particles or platelets.

Claim 22 (original): A product according to claim 17, wherein the chips are in the form of ribbons, wires or filaments.

Claim 23 (previously presented): A product according to claim 17, wherein the matrix is formed of a material chosen from the group consisting of metal, metal alloy and intermetallic materials.

Claim 24 (previously presented): A product according to claim 17, wherein the matrix is formed of a polymeric material.

Claim 25 (previously presented): A product according to claim 17, wherein the matrix is formed of an inorganic material chosen from the group consisting of ceramic materials.